

Figure 1. General reaction scheme of one complete super-cycle isotropic plasma atomic layer etching of nickel aluminide binary intermetallic.

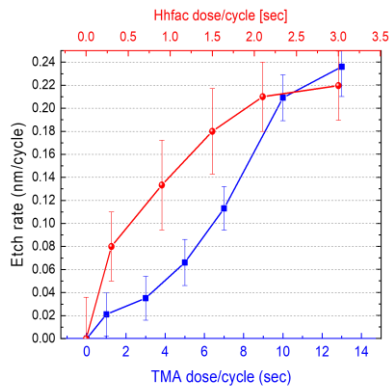


Figure 2. Fundamental ALE study shows the dependency of etch rate of pure *Ni* and *Al* on Hhfac and TMA exposure time/cycle, respectively.

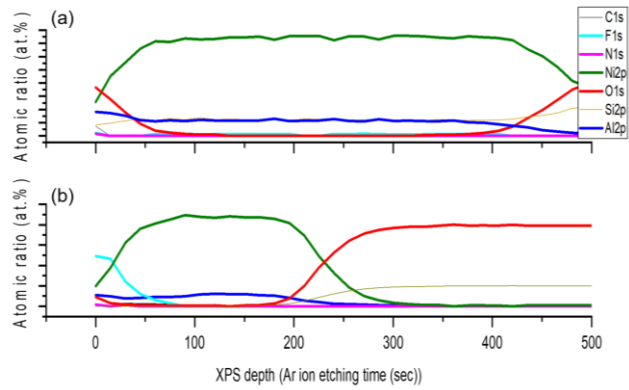


Figure 3. XPS depth profile of *NiAl* films (a) pristine sample (b) after etching by 20 super-cycles.